

SURFACE MOUNT SUPER FAST RECOVERY RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
 - ◆ 260°C/10 seconds at terminals
 - ◆ Glass passivated chip junction

Mechanical Data

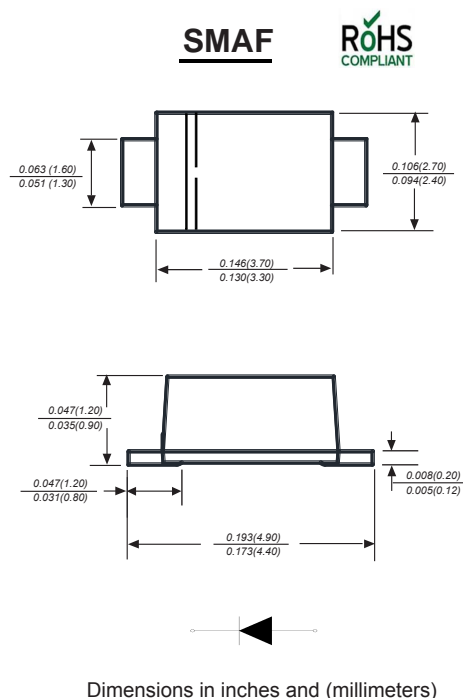
Case : JEDEC SMAF Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0018 ounce, 0.064 grams



Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

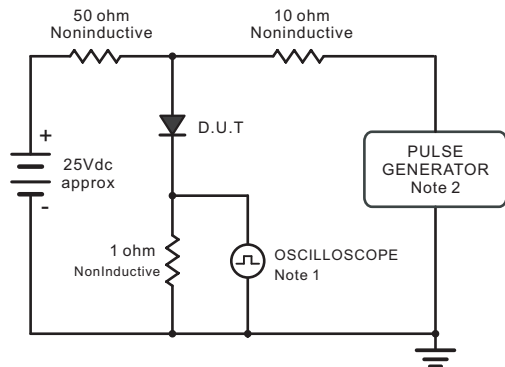
Parameter	SYMBOLS	MDD ES3AF	MDD ES3BF	MDD ES3CF	MDD ES3DF	MDD ES3EF	MDD ES3GF	MDD ES3JF	UNITS
Marking Code									
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	V_{DC}	50	100	150	200	300	400	600	V
Maximum average forward rectified current at $T_L=55^\circ\text{C}$	$I_{(AV)}$	3.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50							A
Maximum instantaneous forward voltage at 3.0A	V_F	0.95			1.25		1.7		V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$	I_R	5.0 200							μA
Maximum reverse recovery time (NOTE 1)	t_{rr}	35							ns
Typical junction capacitance (NOTE 2)	C_J	60.0							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	40.0							$^\circ\text{C}/\text{W}$
Operating junction and storage temperature range	T_J, T_{STG}	-50 to +150							$^\circ\text{C}$

Note: 1. Reverse recovery condition $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$

2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

3. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

Ratings And Characteristic Curves



Note: 1. Rise Time = 7ns, max.
 Input Impedance = 1megohm, 22pF.
 2. Rises Time = 10ns, max.
 Source Impedance = 50 ohms.

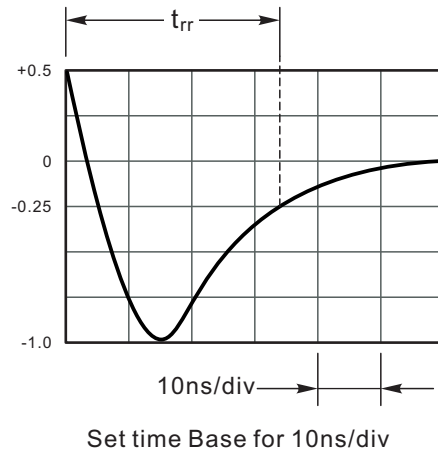


Fig.2 Maximum Average Forward Current Rating

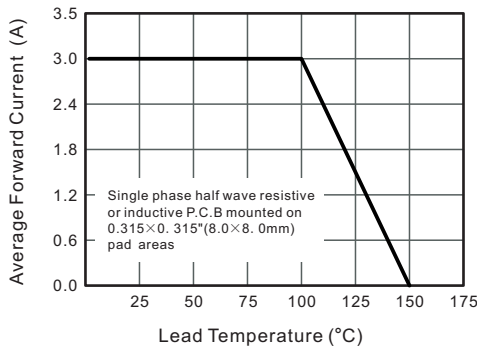


Fig.3 Typical Reverse Characteristics

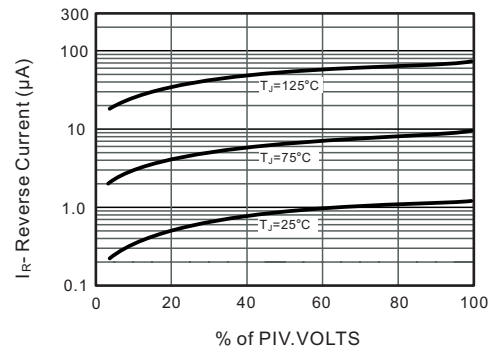


Fig.4 Typical Forward Characteristics

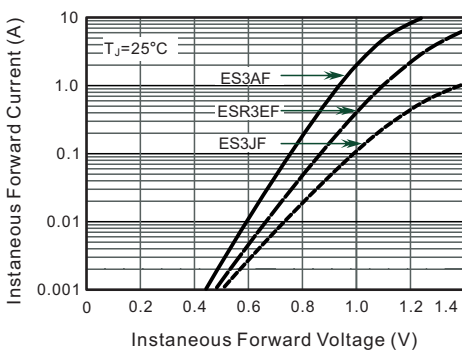
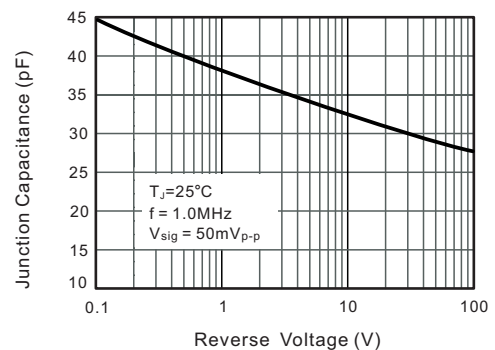
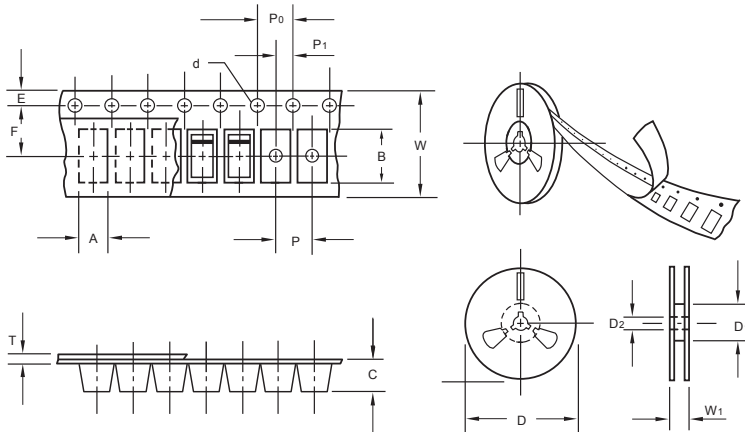


Fig.5 Typical Junction Capacitance



The curve above is for reference only.

Packing information



unit:mm

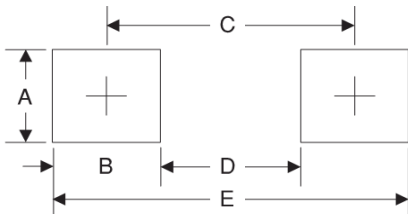
Item	Symbol	Tolerance	SMAF
Carrier width	A	0.1	2.80
Carrier length	B	0.1	4.75
Carrier depth	C	0.1	1.42
Sprocket hole	d	0.05	1.50
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	54.40
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.05
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	8.00
Reel width	W ₁	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMAF	7"	3,000	4.0	6,000	210*208*203	178	400*265*400	120,000	10.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.8	0.071
B	1.6	0.063
C	3.8	0.150
D	2.2	0.087
E	5.4	0.213